GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
RAJYA SABHA
UNSTARRED QUESTION NO. 3884
TO BE ANSWERED ON: 27.03.2026

SEMICONDUCTOR LINKED INVESTMENTS IN ODISHA

3884. SHRI SUBHASISH KHUNTIA:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

(a) whether the Ministry has assessed the extent to which semiconductor-linked industrial investments announced in 2025–26 in Odisha have translated into grounded projects;
(b) if so, the details of investment grounded till date in comparison with total approvals for semiconductor and advanced-electronics units; and
(c) whether any mechanisms exist to ensure time-bound grounding of these projects, if so, the details thereof and if not, the reasons therefor?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (c): Semiconductors is a foundational and strategic industry. Semiconductors are used in almost every device. To promote the development of its manufacturing ecosystem in India, the Government launched Semicon India Programme in January 2022.

The approach of government is driven by Hon'ble PM's vision of Atma Nirbhar Bharat. The focus is on developing the entire value chain of semiconductor ecosystem from design, fabrication, packaging, testing, validation, etc.

In a short span of four years, the Government has approved 10 projects with investment commitments of about Rs. 1.6 lakh crore. Commercial production from one of the plants (Micron) has commenced along with pilot production underway in 3 more plants.

The details of approved semiconductor manufacturing projects in the state of Odisha are as follows:

1. SiCSem Private Limited is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 2,066 crores. The facility will be set up in technology partnership with Clas-SiC Wafer Fab Ltd. for SiC fab and Continental Device India Pvt. Ltd. for packaging.

The production capacity is 5,000 wafers/month, and the packaging capacity is 8 million units/month. Within a short span, the ground-breaking of the plant was also held (November, 2025).

Semiconductor chips from the plant will be used in Electric Vehicles (EVs), Railways, Fast Chargers, Data Centre racks, Consumer Appliances, and Solar Power Inverters.

2. 3D Glass Solutions Inc. (3DGS) is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 1,943 crores. The plant will handle the assembly of packaged products such as Flip Chip Ball Grid Array (FCBGA) assembly, Radio Frequency System in Package (RF SiP), Antenna in Package System in Package (AiP SiP), glass interposers with passives and silicon bridges and 3D Heterogeneous Integration (3DHI) modules.

It will produce about 5,800 panels (glass substrates) and 4.2 million chips will be manufactured every month. The chips from the plants will be used in areas like AI, defence, telecom, RF, High performance computing, automobiles etc.

India Semiconductor Mission regularly monitors the progress of the approved projects.

Design Linked Incentive Scheme
24 projects have been approved for the design of semiconductor chips & SoCs, with a total project value of Rs. 900 crore.

These projects cover chips relating to various critical sectors such as video surveillance, drone detection, energy metering, microprocessors, satellite communications, broadband and IoT SoCs.

In addition, the Government is also providing infrastructure support for chip design to eligible applicants, including access to EDA tools, IP cores, and fabrication facilities. Such infrastructure support is being provided to 103 fabless chip design companies.

Chip to Startup (C2S) Programme
The Government is also providing infrastructure support for chip design to eligible applicants, including access to EDA tools, IP cores, and fabrication facilities.

These advanced designing tools are now available to students of 315 universities/institutes. So far, their usage has exceeded 185 lakh hours.

Using the EDA tools and IPs, 146 chips designs have been taped out by 49 institutions across India out of which SCL, Mohali has successfully fabricated and packaged 94 student-designed chips. The list of beneficiaries of DLI and C2S in the state of Odisha is at **Annexure-I.**

Annexure-I

List of companies approved for EDA tool support under DLI Scheme in the State of Odisha

1. Qualivon Technologies Pvt. Ltd.

List of institutes approved for EDA tool support under C2S in the State of Odisha

1. Parala Maharaja Engineering College, Berhampur
2. National Institute of Technology Rourkela

3. Indian Institute of Technology Bhubaneswar
4. International Institute of Information Technology Bhubaneswar
5. Kalinga Institute of Industrial Technology (KIIT), Bhubaneswar, Odisha
6. Trident Academy of Technology, Bhubaneswar
7. Centurion University of Technology and Management, Odisha
8. Siksha 'O' Anusandhan, Bhubaneswar, Odisha
9. C. V. Raman Global University, Odisha
10. BPUT, Odisha
11. Silicon University, Odisha

****